Initial Product/Process Change Notification

Document #:IPCN26978XA1
Issue Date: 28 Jul 2026

Title of Change:	Update to **IPCN26978XA** - Wafer Fab and Test Site Change for ST3 Products from Mountain Top, USA to Bucheon, Korea.
Proposed First Ship date:	11 Jan 2027 or earlier if approved by customer
Contact Information:	Contact your local onsemi Sales Office
PCN Samples Contact:	Contact your local onsemi Sales Office. Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.
Type of Notification:	This is an Initial Product/Process Change Notification (IPCN) sent to customers. An IPCN is an advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan. The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN). This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 90 days prior to implementation of the change. In case of questions, contact <PCN.Support@onsemi.com>
Marking of Parts/ Traceability of Change:	The changed material can be identified by lot code and date code.
Change Category:	Test Change, Wafer Fab Change
Change Sub-Category(s):	Manufacturing Site Transfer

Sites Affected:

onsemi Sites	**External Foundry/Subcon Sites**
onsemi Bucheon, Korea	None

Description and Purpose:

This Update Notification is to inform customers of the qualification of onsemi Bucheon, Korea facility as NEW wafer fab site for ST3 Technology.

FPCNs to be issued in October of 2026 with first ship date as referenced above from Bucheon fab. If your FPCN approval will extend beyond the proposed first ship date, provide unit requirements for the unchanged material to your onsemi sales representative no later than May 31, 2026, by NCNR PO (Last order date for unchanged material). These bridge quantities will be limited and will be considered on a first-come, first-serve basis.

onsemi will work with customers to facilitate the approval of the FPCNs by providing early samples and matching electrical data upon request, prior to the final PCN notices in October of 2026 to reduce customers' need for additional unchanged material.

Early samples are processed according to final process and condition as released in the FPCN. No changes will occur between early samples and after FPCN issuance.

	Before Change Description	**After Change Description**
FAB Site	Mountain Top, PA, USA	Bucheon, Korea
Backgrind Site	Mountain Top, PA, USA	Bucheon, Korea
Probe Site	Mountain Top, PA, USA and Bucheon, Korea	Bucheon, Korea
OPN naming	No change	-BK suffix added

Qualification Plan:

QV DEVICE NAME : FDS6681Z
RMS : 98262
PACKAGE : SOIC-8

Test	Specification	Condition	Interval
High Temperature Reverse Bias	JESD22-A108	Tj = Max rate Tj for device, bias =100% of rated V (Not to exceed max rated)	1,008 hrs
High Temperature Gate Bias	JESD22-A108	Tj = Max rate Tj for device, Max Vgs	1,008 hrs
High Temperature Storage Life	JESD22-A103	Ta =Max rate storage temp for device	1,008 hrs
Precondition (PC)	J-STD-020, JESD22-A113	IR reflow at 245C or 260C (pkg dependant)	-
(PC+) Highly Accelerated Stress Test	JESD22-A110	Temp = 130C, 85% RH, ~ 18.8 psig, bias = 80% of rated V or 100V max	96 hrs
(PC+) Unbiased Highly Accelerated Stress Test	JESD22-A118	Temp = 130C, RH=85%, ~ 18.8 psig	96 hrs
(PC+) Temp Cycling	JESD22-A104	Temp = -55°C to +150°C	1,000 cyc
(PC+) Intermittent Operating Life	MIL STD750, M 1037, AEC Q101	Ta=+25°C, deltaTj=100°C max, 2 min Ton=Toff	15,000 cyc

List of Affected Parts:

Note: *Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the* ***PCN Customized Portal****.*

Current Part Number	New Part Number	Qualification Vehicle
FDS6681Z	FDS6681Z-BK	FDS6681Z
FDS6679AZ	FDS6679AZ-BK	FDS6681Z
FDS6675BZ	FDS6675BZ-BK	FDS6681Z
FDS6673BZ	FDS6673BZ-BK	FDS6681Z
FDS4935BZ	FDS4935BZ-BK	FDS6681Z
FDS4435BZ	FDS4435BZ-BK	FDS6681Z
FDMC510P	FDMC510P-BK	FDS6681Z
FDMA530PZ	FDMA530PZ-BK	FDS6681Z
FDMA507PZ	FDMA507PZ-BK	FDS6681Z
FDMA3023PZ	FDMA3023PZ-BK	FDS6681Z
FDMA1029PZ	FDMA1029PZ-BK	FDS6681Z
FDMA1023PZ	FDMA1023PZ-BK	FDS6681Z
FDC642P	FDC642P-BK	FDS6681Z
FDC638APZ	FDC638APZ-BK	FDS6681Z

FDC610PZ-G	FDC610PZ-G-BK	FDS6681Z
FDC610PZ	FDC610PZ-BK	FDS6681Z
FDC608PZ	FDC608PZ-BK	FDS6681Z
FDY1002PZ	FDY1002PZ-BK	FDS6681Z
FDY102PZ	FDY102PZ-BK	FDS6681Z
FDMS6673BZ-NC	FDMS6673BZ-NC-BK	FDS6681Z
FDMS4435BZ-NC	FDMS4435BZ-NC-BK	FDS6681Z
FDC638APZ-PSBMS001	FDC638APZ-PSBMS001-BK	FDS6681Z
FDC638APZ-SBMS001	FDC638APZ-SBMS001-BK	FDS6681Z
FDMC4435BZ-F127	FDMC4435BZ-F127-BK	FDS6681Z
FDMC6675BZ-P	FDMC6675BZ-P-BK	FDS6681Z
FDMS6681Z-P	FDMS6681Z-P-BK	FDS6681Z
FDMS6673BZ	FDMS6673BZ-BK	FDS6681Z
FDMS4435BZ	FDMS4435BZ-BK	FDS6681Z
FDMC6679AZ	FDMC6679AZ-BK	FDS6681Z
FDMC6675BZ	FDMC6675BZ-BK	FDS6681Z
FDMC4435BZ	FDMC4435BZ-BK	FDS6681Z